

Product Environmental Technology Standards

WEB Edition

Magnescale Co., Ltd.



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1 Purposes

This technology standard is intended to observe applicable laws, protect the Earth's environment, and reduce harmful effects on the ecosystem through the prevention of the use of environmental management substances in parts, devices, and other products made up of Magnescale products.

This standard clarifies that substances whose use is prohibited, substances whose use is to be fully abolished, and items outside the scope of this standard.

In addition, Magnescale Co., Ltd. complies with customer demands of the Green purchadsing program and others.

2 Scope

2.1 Scope of application for parts/materials

Parts/materials, other articles Magnescale Co., Ltd. consigned their design and fabrication to our suppliers.

The targets shall meet reference values specified in this standard.

- 1) Targeted Parts and Materials
- 2) Half-finished products (assembly parts including functional units, modules, board assemblies and optical fiber assemblies),
- 3) Parts (electric parts, mechanical parts, semiconductor devices, printed circuit boards, recording media, and packaging and materials), and screws.
- 4) Accessories (AC adapters, cable assemblies and supplied parts for using equipment)
- 5) Indirect materials used in products (including materials used in adhesive tape, solder material, unity band, labels, adhesive agents, etc.)
- 6) Printed matters (including operating manuals, warrantees, and supplemental information regarding products and parts)
- 7) Maintenance and repair parts
- 8) Packaging and materials defined in 5.1 "Definition of package parts and materials," used for transportation and protection of parts by the delivery agent.

2.2 Scope of application for products

- 1) Magnescale products designed, manufactured, sold, leased or distributed by Magnescale Co., Ltd.
- 2) Magnescale products outsourced to the third parties to design and manufacture, and sold, leased or distributed under the Magnescale brand
- 3) Third parties' products outsourced to Magnescale Co., Ltd to design and manufacture However parts/materials disignated by a third party are excluded from the scope of application.

Furthermore, even if not explicitly defined in this standard, in the event that substances and associated applications prohibited and/or restricted by ordinance and regulatory requirements in each country, the ordinance and regulatory requirements shall be observed.



3 Terms and definitions

- 3.1 Environment-related substances to be controlled (Controlled Substances)
- Accumulative/persistent/carcinogenic/reprotoxy substances that are likely to adversely affect the human body and prohibited and/or restricted by ordinance and regulatory requirements in each country
- 2) Substances that are restricted by customer's green procurement standard, and also the substances that are judged as necessary to be restricted by Magnescale Co., Ltd.
 - In the event that Magnescale standard is unable to satisfy an external requirement, external requirement shall have priority, and the substances shall also be controlled on a case-by-case basis.
- 3) Substances that are contained in parts and/or semiconductor devices and judged by Magnescale Co., Ltd. to have a significant impact on environment and/or human body

3.2 Management level

Terms used in these management levels are defined as given below.

1) Level 1

The substances and their applications classified into this level are those that are banned for the use in parts and materials.

2) Level 2

On the date set in each table, the substances and their applications in the respective tables shall be reclassified into Level 1.

3) Level 3

Considering possibility of phase-out in the future (i.e. reclassification into Level 2), technical investigations on substances and their applications are conducted.

4) Exception

Substances and applications not covered by the above 1) to 3) due to exceptions from laws.

Where needed, we investigate the useage of substances and their applications.

3.3 Contained

The condition that a substance remains in materials used for part and/or semiconductor device by addition, filling, mixture or adhesion, regardless of one's intention.

Even in the case a substance unintentionally got mixed in or adhered to a product in a processing process, we also consider this as "contained".

3.4 Intentional addition

The condition that a substance remains in materials used for parts and/or semiconductor devices by intentional addition, filling, mixture or adhesion to give a specific characteristic, appearance, property, attribute or quality.

- With respect to the substance which is contained in a natural material and technically not possible to be completely removed by the refining process, also the substance which is generated by the synthesis reaction and technically not possible to be completely removed, those substances are judged as impurities and not considered as "intentional addition".
- 2) With respect to the substances called "impurities" which are distinguished from main material, when they are used for the purpose of changing a characteristic of the material such as alloys, it is not considered as "intentional addition".

However for dopants to produce semiconductor devices, etc., even when extremely small amount is remaining, it is not considered as "intentional addition".



3.5 Target

Elements (parts, materials, useage, processing) that require to be controlled according to each "management level (described in 3.2)".

3.6 Criteria/threshold level

This criteria/threshold level means each "management level (described in 3.2)" or numerical value.

- 1) When "numerical value" is specified in "criteria/ threshold level" of "level 1", and the Controlled Substances is contained as impurities in a part or a semiconductor device, etc., its density must not reach the "numerical value".
- 2) When conditions such as "the intentional addition" and "numerical value" are shown in "the criteria/threshold level", it is necessary to meet both conditions.
- 3) When "measurement target" is set for a controlled substance, measurement shall be done according to "standard for measurement".

3.7 Effective date of the ban on the delivery

This indicates the date on or after which Magnescale Co., Ltd. won't accept the parts and/or materials specified in the corresponding columns of Table 4.1.

3.8 Plastic

Plastics refer to materials and raw materials composed of synthetic high-molecular polymers in this standard. More specifically, "plastics" mainly mean the following articles composed of synthetic high-molecular polymers: resins, films, adhesives, adhesive tapes, molded products, products made of synthetic rubber, and plastics made from raw materials of plant origin.

3.9 RoHS directive

RoHS is the abbreviation of "Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (2011/65/EU)".

It is one of EU regulations and prohibits the sale of electricity, electronic goods containing lead, mercury, cadmium, hexivalent chrome or a bromine-based fire retardant (PBB and PBDE) in EU market after July 1, 2006.

3.10 REACH regulation

REACH is the abbreviation of "Registration, Evaluation, Authorization and Restriction of Chemicals (1907:2006)". It is one of EU regulations effective as of June 1, 2007, and is the general regulation for registering, evaluating, authorizing, regulating chemical substances.

Manufacturers and importers who provide molded products in the EU market are obligated under certain conditions to evaluate and register substances and also to provide chemical substance information contained in molded articles.

The substances which are contained in molded articles and their contained information is required to be provided are called SVHC (substance of very high concern).

The list of SVHC is growing step by step.



3.11 POPs treaty

POPs treaty is "The Stockholm Convention on Persistent Organic Pollutants".

POP is the abbreviation of "Persistent Organic Pollutants".

Out of the bromine-based fire retardants which are the substances prohibited by RoHS directive, PBDE is considered as a candidate substance for POPs.

3.12 RoHS regulation for Turkey

Six Controlled Substances are lead, mercury, cadmium, hexivalent chrome, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenylethers).

The threshold for cadmium is 100ppm, the threshold for other materials are 1,000ppm.

The thresholding for homogeneous materials are the same as European RoHS directive.

The target electric equipment is the same, but the exclusion rules (exclusion item) are slightly different.

Because Turkey is not an EU member state, it is not regulated by the RoHS directive.



4 Management standards for environment-related substances to be controlled

4.1 Environment-related substances to be controlled

The table below lists the Controlled Substances defined in this Standard.

Table 4.1 List of Controlled Substances			
Controlled Substances			
Cadmium and cadmium compounds			
Lead and lead compounds			
Mercury and mercury compounds			
Hexavalent chromium compounds			
Polychlorinated biphenyls (PCB),			
Polychlorinated naphthalenes (PCN),			
Polychlorinated terphenyls (PCT)			
Short-chain chlorinated paraffins (SCCP)			
Polyvinyl chloride (PVC) and PVC blends			
Tris(2-chloroethyl) phosphate (TCEP), Tris(2-chloro-1-methylethyl) phosphate (TCPP),			
Tris(1,3-dichloro-2-propyl) phosphate (TDCPP)			
Other chlorinated organic compounds			
Polybrominated biphenyls (PBB)			
Polybrominated diphenylethers (PBDE)			
including decabromodiphenyl ether (DecaBDE)			
Hexabromocyclododecane (HBCDD)			
Other brominated organic compounds			
Trisubstituted organotin compounds (including tributyltin (TBT) compounds and triphenyltin (TPT) compounds)			
Dibutyltin (DBT) compounds			
Dioctyltin (DOT) compounds			
Asbestos			
Specific azo compounds			
Formaldehyde			
Specific benzotriazole			
Dimethyl fumarate (DMF)			
Beryllium oxide			
Beryllium copper			
Cobalt dichloride			
Diarsenic trioxide, Diarsenic pentaoxide			
Bis (2-ethylhexyl)phthalate, Dibutyl phthalate,			
Benzyl butyl phthalate, Diisobutyl phthalate			
Di-isononyl phthalate, Di-isodecyl phthalate, Di-n-octyl phthalate, Di-n-hexyl phthalate,			
"1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich",			
"1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters", Bis(2-methoxyethyl) phthalate,			
Diisopentylphthalate, "1,2-Benzenedicarboxylic acid, dipentylester, branched and linear", N-pentyl-isopentylphthalate			
Dipentyl phthalate			
Hydrofluorocarbon (HFC), Perfluorocarbon (PFC), Sulfur hexafluoride (SF ₆)			
Ozone depleting substances (ODS)			
Perfluorooctane sulfonates (PFOS)			
Boric acid, specific sodium borates			
4-(1,1,3,3-tetramethylbutyl) phenol			
Bis(2-methoxyethyl) ether			
N,N-dimethylacetamide (DMAc)			
Ethylene glycol dimethyl ether (EGDME)			
Perchlorates			
Perfluorooctanoic acid (PFOA) and individual salts and esters of PFOA			
Polycyclic aromatic hydrocarbons (PAH)			
Trixylyl phosphate (TXP)			
Radioactive materials			
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4.2 Main "Targets" and "Effective date of the ban on the delivery" regarding 'Controlled Substances'

1) Cadmium and cadmium compounds

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	 Plastics (including rubbers) Note: Insulation of wires, cables and cords are defined as plastics (including rubbers). Paints Inks Solders All applications other than the above See 5 Additional rules for packaging components and materials. 	 100 ppm or more of the cadmium in homogeneous materials. (*1) More than 20 ppm of the cadmium in solder. 100 ppm or more of the cadmium in homogeneous materials. 	Banned
Exemption	Plating of electrical contacts, for which highOptical glasses		as no alternative materials.
*1 Note	 Test objects: plastics (including rubbers), paints, and inks Threshold level: less than 100 ppm 		
Standards for measurement	Typical sample preparation methods: e.g. IEC 62321:2013, EPA 3052:1996 - Closed system for acid decomposition method (e.g. microwave decomposition method) - Acid digestion method - Dry ashing method (to heat a sample around 500 degrees Celsius in the air, and to burn and become ash) Note: Precipitates must be completely dissolved by some technical means (e.g. alkali fusion). Any extraction methods (including EN71-3:1994, ASTM F 963-96a, ASTM F 963-03, ASTM D 5517 and ISO 8124-3:1997) shall not be applied.		
	Measurement methods Typical measurement methods: e.g. IEC 62 Inductively Coupled Plasma-Optical (A-Atomic Absorption Spectroscopy (AAS-Inductively Coupled Plasma-Mass Spectroscopy) Note:	Atomic) Emission Spectroscopy (S) ectroscopy (ICP-MS)	
	If a combination of a sample preparation me quantification for cadmium is less than 5 pp		



2) Lead and lead compounds

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	 Plastics (including rubbers) Note: Insulation of wires, cables and cords are defined as plastics (including rubbers). Paints Inks All applications other than the above See 5 Additional rules for packaging components and materials. 	More than 100 ppm (or 0.01 wt%) of the lead in homogeneous materials (*2) 1000 ppm (or 0.1 wt%) or more of the lead in homogeneous materials	Banned
Exemption	 Lead in glass of fluorescent tubes not excellent Lead as an alloying element in steel for ma 0.35% lead by weight Lead as an alloying element in aluminium of Copper alloy containing up to 4% lead by weight High melting temperature type solders (i.e., Glass, glass matrix compound, ceramic or electronic components (e.g. piezoelectroni) Dielectric ceramic in capacitors for a rated discrete semiconductors Optical glass, filter glass Solder to complete a viable electrical connicircuit flip chip packages Lead in cermet-based trimmer potentiometer 	containing purposes and in galvanic containing up to 0.4% lead by we weight I lead based alloys containing 85 ceramic matrix compound, which ic devices) Note that dielectric ce voltage of 125 V AC or 250 V DC erials for capacitors which are par-	wt% by weight or more lead) in is used in electrical and ramic in capacitors is excluded or higher rt of integrated circuits or
*2 Note	Test objects: plastics (including rubbers), p Threshold level: Up to 100 ppm		
Standards for measurement	Sample preparation Typical sample preparation methods: e.g. Closed system for acid decomposition Acid digestion method Dry ashing method (to heat a sample a ash) Note: Precipitates must be completely dissolved Any extraction methods (including EN71-ISO 8124-3:1997) shall not be applied.	method (e.g. microwave decomparound 500 degrees Celsius in the	e air, and to burn and become alkali fusion).
	Additionally, EN1122:2001 is not applied. Additionally, EN1122:2001 is not applicable. Measurement methods Typical measurement methods: e.g. IEC 6 Inductively Coupled Plasma-Optical (A Atomic Absorption Spectroscopy (AAS Inductively Coupled Plasma-Mass Spectroscopy (AAS Inductively Coupled Plasma-Mass Spectroscopy (AAS) Inductively Coupled Plasma-Mass Spectroscopy (AAS) Note: If a combination of a sample preparation requantification for lead is less than 30 ppm.	52321:2013 Atomic) Emission Spectroscopy (IS) ectroscopy (ICP-MS) method and a measurement metl	



3) Mercury and mercury compounds

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	All applications (paint, inks etc.) See 5 Additional rules for packaging components and materials	- Intentionally added - 1000 ppm (or 0.1 wt%) or more of the mercury in the homogeneous materials	Banned
Exemption	 Mercury in cold cathode fluorescent lamps Short length (not over 500 mm): Medium length (over 500 mm and not over Long length (over 1500 mm): Mercury in high-pressure gas discharge lam 	Not exceeding 3. 1500 mm): Not exceeding 5 Not exceeding 10	uorescent lamps (EEFL): .5 mg of mercury per lamp mg of mercury per lamp 0 mg of mercury per lamp
*3 Note	 When "Intentionally added" and a numerical value are shown in "Criteria/threshold levels", both of them shall be satisfied. 		
Standards for measurement	 IEC 62321:2013, EPA 3052:1996 EPA Sealing up the acidolysis method (e.g. for a microwave elucidation) The heating vaporization cold water atomic absorption method Elucidation for the sulfuric acid using the resolution flask (the Kjeldahl method) with reflux condenser, wet process with the nitric acid in both methods Pay attention so that mercury does not evapolate In addition, if the sediment occurs, completely dissolves by some kind of methods, and become solution 		

4) Hexavalent chromium compounds

	Targets	Criteria/threshold levels (*4)	Effective date of the ban on the delivery
Level 1	Surfaces of screws, steel sheets, etc.that are processed with plating or conversion coating (*4A).	- Residue on the processed surface (*4B)	Banned
	All applications other than the above See 5 Additional rules for packaging components and materials.	Intentionally added 1000 ppm (or 0.1 wt%) or more of the hexavalent chromium in the homogeneous materials	
*4 Note	- When "Intentionally added" and a numerical value are shown in "Criteria/threshold levels", both of them shall be satisfied.		
*4A Note	 By the Raydent processing (to precipitate a lot of ceramic-formed chromic fine particles with less than about 1 μm dia by an electrochemical reaction), a hexivalent chrome compound may be produced by the unevenness of the film formation condition. To confirm that residual density is less than a measurement limit in a pulling out examination. 		
*4B Note	 Residue on the processed surface is banned for surface processing. 	l in Level 1. Not applicable to hex	avalent chromium compounds

5) Polychlorinated biphenyls (PCB), Polychlorinated naphthalenes (PCN), Polychlorinated terphenyls (PCT)

5)-1 Polychlorinated biphenyls (PCB)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (insulating oil for condensers, etc.)	Intentionally added50 ppm (or 0.005 wt%) or more of the materials	Banned

5)-2 Polychlorinated naphthalenes (PCN)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (cable insulations, etc.)	- Intentionally added	Banned

5)-3 Polychlorinated terphenyls (PCT)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (insulating oil, etc.)	- 50 ppm (or 0.005 wt%) or more of the materials	Banned



6) Short-chain chlorinated paraffins (SCCP) (*6)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (flame retardants, etc.)	 Intentionally added More than 1000 ppm (or 0.1 wt%) of the materials 	Banned
*6 Note			

7) Polyvinyl chloride (PVC) and PVC blends

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	 Cable ties used for accessories and connecting cords Packaging components and materials to protect, contain, or transport products or supplied accessories (e.g. bags, adhesive tapes, cartons, and blister packs) Heat shrink tubes Flexible flat cables (FFC) Insulating plates, decorative panels,labels, sheets, and laminates 	- Intentionally added	Banned
Level 3	- All applications other than Level 1	- Intentionally added	N/A
Exception	Magnetic paints		
	- Binder for resins used for paints, inks, coating agents, adhesives etc.		
	- Dustlip for scale system		

8) Tris(2-chloroethyl) phosphate (TCEP), Tris(2-chloro-1-methylethyl) phosphate (TCPP),

Tris(1,3-dichloro-2-propyl) phosphate (TDCPP) (*8)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	Flame retardants used in plastics, resins, fabrics, and textiles	- More than 1000 ppm (or 0.1 wt%) of the parts	Banned
*8 Note	- CAS No.115-96-8, 13674-84-5, 13674-87-8		

9) Other chlorinated organic compounds

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	Flame retardants used for printed wiring board laminate	More than 900 ppm (0.09 wt%) chlorine content by weight in the laminate	N/A
	- Flame retardants or plasticizers contained in plastic parts other than the above	- Intentionally added	

10) Polybrominated biphenyls (PBB) (*10)

	Targets	Criteria/threshold levels (*10)	Effective date of the ban on the delivery
Level 1	- All uses (flame retardants, etc.)	Intentionally added 1000 ppm (or 0.1 wt%) or more in the homogeneous materials	Banned
*10 Note	- When "Intentionally added" and a numerical be satisfied.	value are shown in "Criteria/thres	shold levels", both of them shall



11) Polybrominated diphenylethers (PBDE) including decabromodiphenyl ether (DecaBDE) (*11)

	Targets	Criteria/threshold levels (*11)	Effective date of the ban on the delivery
Level 1	- All uses (flame retardants, etc.)	 Intentionally added 1000 ppm (or 0.1 wt%) or more in the homogeneous materials 	Banned
*11 Note	- When "Intentionally added" and a numerical be satisfied.	value are shown in "Criteria/thres	shold levels", both of them shall

12) Hexabromocyclododecane (HBCDD) (*12)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (flame retardants, etc.)	 Intentionally added More than 1000 ppm (or 0.1 wt%) in the parts 	Banned
*12 Note	The target substances are following 14 materials - CAS No. 25637-99-4, 3194-55-6, 4736-49-6, 65701-47-5, 169102-57-2, 678970-15-5, - When "Intentionally added" and a numerical be satisfied.	134237-50-6, 134237 138257-17-7, 138257 678970-16-6, 678970	7-51-7, 134237-52-8, 7-18-8, 138257-19-9, 1-17-7

13) Other brominated organic compounds

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	Flame retardants used for printed wiring board laminate	- More than 900 ppm (0.09%) bromine content by weight in the laminate	N/A
	- Flame retardants or plasticizers contained in plastic parts other than the above	- Intentionally added	

14) Trisubstituted organotin compounds (including tributyltin (TBT) compounds and triphenyltin (TPT) compounds) (*14)

	Targets		Criteria/threshold levels (*14A)	Effective date of the ban on the delivery
Level 1	-	All uses (paints, etc.)	 Intentionally added More than 1000 ppm (or 0.1 wt%) of the tin contained in materials (*14B) 	Banned
*14 Note	-	Metal tin, tin alloys, tin plating and tin inorganic compounds do not fall under this category.		
*14A Note	-	When "Intentionally added" and a numerical value are shown in "Criteria/threshold levels", both of them shall be satisfied.		
*14B Note	-	For materials, it is containment more than 1,0	000 ppm by tin conversion.	

15) Dibutyltin (DBT) compounds (*15)

	Targets	Criteria/threshold levels (*15A)	Effective date of the ban on the delivery
Level 1	All applications including additives of plastics	More than 1000 ppm (or wt%) of the tin contained in materials	Banned
Exception	Additives of reused packaging components and materials for parts and devices Additives of packaging components or materials for devices, semiconductors, and any other components (e.g. trays, magazine sticks, stoppers, reels, embossed carrier tapes)		
*15 Note	Metal tin, tin alloys, tin plating and tin inorganic compounds do not fall under this category. Two butyls are a tin atom and the compounds which covalently linked.		
*15A Note	For materials, it is containment more than 1,000 ppm by tin conversion.		



16) Dioctyltin (DOT) compounds (*16)

	Targets		Criteria/threshold levels	Effective date of the
			(*16A)	ban on the delivery
Level 1	-	Additives of textiles	 More than 1000 ppm (or 	Banned
			0.1 wt%) of the tin	
			contained in materials	
*16 Note	-	Metal tin, tin alloys, tin plating and tin inorganic compounds do not fall under this category.		
*16A Note	-	For materials, it is containment more than 1,000 ppm by tin conversion.		

17) Asbestos

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (insulators, heat shield material, etc.)	- Intentionally added	Banned

18) Specific azo compounds (*18)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- Additives of textiles and leathers	 More than 30 ppm (or 0.003 wt%) in materials 	Banned
*18 Note	- Azodyes that form any of the amine compounds listed in Table 4.2.2 through the decomposition methods cited in REACH Regulation (EC) No. 1907/2006 / Annex XVII and amine compounds in Table 4.2.2.		
Standards for measurement	- The methods for decomposing azo compounds and then extracting amines are as follows EN 14362-1:2012 - EN 14362-2:2012		



Table 4.2.1 List of specific amine compounds

92-87-5	CAS No.	Name and Chemical formula of amine compounds
Chemical formula: C ₁₂ H ₁₂ N ₂ 92-87-5 Benzidine Chemical formula: C ₁₂ H ₁₂ N ₂ 95-69-2 4-chlorotoluidine; 4-chloro-2-methylaniline Chemical formula: C ₁₃ H ₁₂ N ₂ 91-59-8 2-naphtylamine Chemical formula: C ₁₃ H ₁₅ N ₃ 97-56-3 0-aminoazotoluene Chemical formula: C ₁₃ H ₁₅ N ₃ 99-55-8 2-amino-4-nitroluene; 5-nitro-o-toluidine Chemical formula: C ₁₃ H ₁₅ N ₃ 99-55-8 2-amino-4-nitroluene; 5-nitro-o-toluidine Chemical formula: C ₁₃ H ₁₅ N ₂ 106-47-8 0-chioroaniline Chemical formula: C ₁₃ H ₁₅ N ₂ 101-77-9 4-4-diaminodiphenyimethane; 4,4'-methylenedianiline Chemical formula: C ₁₃ H ₁₅ N ₂ 119-94-1 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,3'-dimethoxybenzidine Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 3,4'-diaminodiphenyimethane; 4,4'-diamino-3,3'-diphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-93-7 2,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-95-1 4,4'-oxideaniline Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-95-1 4,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₂ 119-95-1 4,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₃ 119-95-1 4,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₃ 119-95-1 4,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyimethane Chemical formula: C ₁₃ H ₁₅ N ₂ O ₃ 119-95-1 4,4'-diaminodiphenyimethane; 4,4'-diaminodiphenyime	92-67-1	
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95-69-2 4-chloro-o-toluidine; 4-chloro-2-methylaniline 91-59-8 2-naphtylamine 97-56-3 0-aminoazotoluene Chemical formula: C ₁₄ H ₁₆ N ₃ 99-55-8 2-amino-4-nitroluene; 5-nitro-o-toluidine Chemical formula: C ₁₄ H ₁₆ N ₃ 106-47-8 p-chloroaniline Chemical formula: C ₁₄ H ₀ N ₂ O 101-77-9 p-chloroaniline Chemical formula: C ₁₄ H ₁₆ N ₂ O 101-77-9 4,4*-diaminodiphenylmethane; 4,4*-methylenedianiline Chemical formula: C ₁₃ H ₁₆ N ₂ O 119-94-1 3,3*-direthoxybenzidine Chemical formula: C ₁₂ H ₁₆ N ₂ O 119-93-7 3,3*-dimethylenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O 338-86-0 3,3*-dimethyl-4 -diaminodiphenylmethane; 4,4*-diamino-3,3*-diphenylmethane Chemical formula: C ₁₄ H ₁₆ N ₂ O 33*-dimethyl-4 -diaminodiphenylmethane; 4,4*-diamino-3,3*-diphenylmethane Chemical formula: C ₁₄ H ₁₆ N ₂ O 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₄ H ₁₆ N ₂ O 101-14-4 4,4*-methylene-bis-global characteristics 4,4*-diaminodiphenylmethane; 4,4*-diaminodiphenylmethane; 4,4*-diamino	92-87-5	Benzidine
Chemical formula: C₁H₂CIN 91-59-8 2-naphthylamine Chemical formula: C₁H₂N₂N 97-56-3 0-aminoazotoluene Chemical formula: C₁H₂N₂N₂ 99-55-8 2-amino-4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C₂H₂CIN 615-05-4 2,4-diaminoarisole Chemical formula: C₂H₂CIN 615-05-4 2,4-diaminoarisole Chemical formula: C₂H₂CIN 615-05-4 4,4'-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C₂H₁CN₂O 91-94-1 3,3'-dichlorobenzidine Chemical formula: C₂H₁NO₂O 119-90-4 3,3'-dimethylbenzidine Chemical formula: C₁H₁NO₂O 3,3'-dimethylbenzidine Chemical formula: C₁H₁NO₂ 838-80 0,3'-dimethyl+4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C₁SH₁NO₂ 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁SH₁NO₂ 101-80-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁SH₁NO₂ 95-83-4 0-toluidine Chemical formula: C₁H₂No₂		Chemical formula: C ₁₂ H ₁₂ N ₂
91-59-8 2-naphthylamine Chemical formula: C ₁₀ H ₅ N 97-56-3 0-aminoazotoluene Chemical formula: C ₁₄ H ₁₅ N ₅ 99-55-8 2-amino-4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C ₂ H ₈ N ₂ O ₂ 106-47-8 p-chloroaniline Chemical formula: C ₂ H ₆ CIN 615-05-4 2,4-diaminoanisole Chemical formula: C ₁₅ H ₁₅ N ₂ O 4,4-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C ₁₅ H ₁₅ N ₂ O 19-94-1 3,3'-dichlorobenzidine Chemical formula: C ₁₅ H ₁₆ N ₂ O ₂ 119-90-4 3,3'-dimethyoxybenzidine Chemical formula: C ₁₅ H ₁₆ N ₂ O ₂ 838-88-0 3,3'-dimethylbenzidine Chemical formula: C ₁₅ H ₁₆ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₅ H ₁₆ N ₂ 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₅ H ₁₂ O ₂ N 101-80-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₅ H ₁₂ O ₂ N 195-63-4 o-toluidine Chemical formula: C ₁₇ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₁₇ H ₁₀ N ₂ 137-17-7 2,4-5 trimethylaniline Chemical formula: C ₁₇ H ₁₀ N ₂ 137-17-7 2,4-5 trimethylaniline Chemical formula: C ₁₇ H ₁₀ N ₂ 137-17-7 2,4-5 trimethylaniline Chemical formula: C ₁₇ H ₁₀ N ₂	95-69-2	4-chloro-o-toluidine; 4-chloro-2-methylaniline
Chemical formula: C₁₀H₅N 97-56-3 0-aminoazotoluene Chemical formula: C₁+H₁₅N₃ 99-55-8 2-amino-4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C₁+H₃N₂O₂ 106-47-8 p-chloroaniline Chemical formula: C₂+H₃ON₂O 615-05-4 2,4-diaminoanisole Chemical formula: C₁+H₃N₂O₂ 101-77-9 4,4-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C₁+H₃N₂O₂ 119-94-1 3,3-dichlorobenzidine Chemical formula: C₁+H₃N₂O₂ 119-90-4 3,3-dimethylenexybenzidine Chemical formula: C₁+H₁₅N₂O₂ 3,3-dimethylenexybenzidine Chemical formula: C₁+H₁₅N₂O₂ 388-80 3,3-dimethyl-4,4-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C₁+H₁₅N₂O 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁+H₁₅N₂O 101-80-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁+H₂N₂O 95-53-4 0-foluidine Chemical formula: C₁+H₂N₂O 95-60-7 2,4-foluylenediamine; 4,methyl-m-phenylenediamine Chemical formula: C;H₃N 95-80-7 2,4-foluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C;H₃NO 0-emiscal formula: C;H₃NO 0-chemical formula: C;H₃NO 0-chemical formula: C;H₃NO 0-chemical formula: C;H₃NO 0-ch		Chemical formula: C ₇ H ₈ CIN
97-56-3 o-aminoaztoluene Chemical formula: C ₁₄ H ₁₆ N ₃ 99-55-8 2-amino4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C ₇ H ₈ N ₂ O ₂ 106-47-8 p-chloroaniline Chemical formula: C ₆ H ₆ CIN 615-05-4 2,4-diaminoanisole Chemical formula: C ₇ H ₁₀ N ₂ O 101-77-9 4,4-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C ₁₃ H ₁₄ N ₂ 91-94-1 3,3'-dichlorobenzidine Chemical formula: C ₁₂ H ₁₀ C ₂ N ₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₄ H ₁₆ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₃ H ₁₇ O ₂ N 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ O ₂ N 101-80-4 4,4'-withidamiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ O 95-53-4 0-toluidine Chemical formula: C ₁₇ H ₁₀ N ₂ 137-17-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4-stimethylaniline Chemical formula: C ₇ H ₁₀ N ₂ 0-benical formula: C ₇ H ₁₀ N ₂ 4-chilylenediamine; 4-m	91-59-8	2-naphthylamine
Chemical formula: C14H15N3 99-55-8 2-amino-4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C2H ₈ N₂O₂ 106-47-8 p-chloroaniline Chemical formula: C2H ₈ ClN 615-05-4 2,4-diaminoanisole Chemical formula: C3H10N₂O 101-77-9 4,4-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C13H16N2 91-94-1 3,3'-diichlorobenzidine Chemical formula: C12H16O₂N2 119-90-4 3,3'-diimethylbenzidine Chemical formula: C14H16N2O2 119-93-7 3,3'-diimethylbenzidine Chemical formula: C14H16N2 288-88-0 3,3'-diimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C15H16N2 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C15H16N2 101-80-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C13H12ON 101-80-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C12H12N2O 139-65-1 4,4'-toldeaniline; 4,4'-diaminodiphenylsulfide Chemical formula: C12H12N2 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C2H3NN 90-04 0-folnical formula: C2H3NN 60-09-3 4-aminoazobenzene		
99-55-8 2-amino-4-nitrotoluene; 5-nitro-o-toluidine Chemical formula: C ₂ H ₈ N ₂ O ₂ 106-47-8 p-chlorosaliline Chemical formula: C ₂ H ₆ CIN 615-05-4 2,4-diaminoanisole Chemical formula: C ₁ H ₁₀ N ₂ O 101-77-9 4,4-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C ₁₃ H ₁₄ N ₂ 91-94-1 3,3-dichlorobenzidine Chemical formula: C ₁₂ H ₁₀ C ₂ N ₂ 119-90-4 3,3-dimethylosprzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₈ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₅ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chlororanilene) Chemical formula: C ₁₃ H ₁₁ C ₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ N 95-80-7 2,4-toluidine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4-toluidine Chemical formula: C ₇ H ₁₀ N ₂ 0-douidine Chemical formula: C ₇ H ₁₀ N ₂ 0-douidine Chemical formula: C ₇ H ₁₀ N ₂ 0-douidine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7	97-56-3	o-aminoazotoluene
Chemical formula: C ₇ H ₈ N ₂ O ₂ P-chloroaniline Chemical formula: C ₈ H ₉ CIN		
Dechloroanilline Chemical formula: C ₆ H ₆ CIN	99-55-8	·
Chemical formula: C ₆ H ₆ CIN 615-05-4 2,4-diaminoaisole Chemical formula: C ₇ H ₁₀ N ₂ O 101-77-9 4,4'-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C ₁₃ H ₁₄ N ₂ 91-94-1 3,3'-dichlorobenzidine Chemical formula: C ₁₂ H ₁₀ C ₁₂ N ₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 33'-dimethyl-4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₄ H ₁₆ N ₂ 838-8-0 3,3'-dimethyl-4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₆ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₅ H ₁₆ N ₂ 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 0-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₉ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene		
615-05-4 2,4-diaminoanisole Chemical formula: C;H₁₀N₂O 101-77-9 4,4'-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C₁₂H₁₀N₂O 91-94-1 3,3'-dichlorobenzidine Chemical formula: C₁₂H₁₀N₂O₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C₁₄H₁₀N₂O₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C₁₄H₁₀N₂ 288-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C₁₅H₁₃N₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C₂₅H₁₃N₂ 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁₃H₁₂C₂N 101-80-4 4,4'-oxideaniline Chemical formula: C₁₂H₁₂N₂O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C₁₂H₁₂N₂S 95-53-4 0-toluidine Chemical formula: C₁H₀N₂ 2,4,5-trimethylaniline Chemical formula: C₁H₀N₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C₁H₃N 0-0-09-3 4-aminoazobenzene	106-47-8	!
Chemical formula: C₁H₁₀N₂O 101-77-9 4,4'-diaminodiphenylmethane; 4,4'-methylenedianiline Chemical formula: C₁₂H₁₀N₂ 91-94-1 3,3'-dichlorobenzidine Chemical formula: C₁₂H₁₀N₂O₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C₁₄H₁₀N₂O₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C₁₄H₁₀N₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C₁₅H₁₀N₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C₃H₁₁NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁₂H₁₂N₂O 139-65-1 4,4'-diaminodiphenylsulfide Chemical formula: C₁₂H₁₂N₂O 95-53-4 o-toluidine Chemical formula: C₁₂H₁₂N₂O 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C₁H₁₀N₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C₁H₁₃N 0-anisidine Chemical formula: C₂H₁₃N 0-anisidine Chemical formula: C₂H₁₃N </td <td></td> <td></td>		
101-77-9	615-05-4	·
Chemical formula: C ₁₃ H ₁₄ N ₂ 3,3'-dinchrobenzidine Chemical formula: C ₁₂ H ₁₀ C ₁₂ N ₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 119-93-7 3,3'-dimethyl-denzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 139-93-7 3,3'-dimethyl-denzidine Chemical formula: C ₁₄ H ₁₆ N ₂		
91-94-1 3,3'-dichlorobenzidine Chemical formula: C ₁₂ H ₁₀ C ₁₂ N ₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₈ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₈ H ₁₁ NO 101-104-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₇ H ₉ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	101-77-9	
Chemical formula: C ₁₂ H ₁₀ C ₁₂ N ₂ 119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 119-93-7 3,3'-dimethylbenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₆ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-toxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 O-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₉ H ₁₃ N 4-aminoazobenzene		
119-90-4 3,3'-dimethoxybenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 838-88-0 3,3'-dimethylbenzidine Chemical formula: C ₁₅ H ₁₈ N ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₈ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₁₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 0-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	91-94-1	·
Chemical formula: C ₁₄ H ₁₆ N ₂ O ₂ 3,3'-dimethylbenzidine Chemical formula: C ₁₄ H ₁₆ N ₂ 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₅ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 0-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene		
119-93-7 3,3'-dimethylbenzidine Chemical formula: C₁₄H₁₅N₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C₁₅H₁₅N₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C₀H₁₁NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C₁₃H₁₂C₁₂N 101-80-4 4,4'-oxideaniline Chemical formula: C₁₂H₁₂N₂O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C₁₂H₁₂N₂S 95-53-4 0-toluidine Chemical formula: C₁H₂N₂N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C₁H₁₀N₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C₂H₁₃N 90-04-0 0-anisidine Chemical formula: C₂H₃NO 60-09-3 4-aminoazobenzene	119-90-4	
Chemical formula: C ₁₄ H ₁₆ N ₂ 838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane Chemical formula: C ₁₅ H ₁₈ N ₂ 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene		
838-88-0 3,3'-dimethyl-4,4'-diaminodiphenylmethane; 4,4'-diamino-3,3'-diphenylmethane 120-71-8 p-cresidine; 6-methoxy-m-toluidine Chemical formula: C ₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	119-93-7	
$ \begin{array}{c cccc} Chemical formula: C_{15}H_{18}N_2 \\ \hline 120-71-8 & p-cresidine; 6-methoxy-m-toluidine \\ Chemical formula: C_{8}H_{11}NO \\ \hline \hline 101-14-4 & 4,4'-methylene-bis-(2-chloroanilene) \\ Chemical formula: C_{13}H_{12}C_{12}N \\ \hline \hline 101-80-4 & 4,4'-oxideaniline \\ Chemical formula: C_{12}H_{12}N_2O \\ \hline \hline 139-65-1 & 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide \\ Chemical formula: C_{12}H_{12}N_2S \\ \hline \hline 95-53-4 & o-toluidine \\ Chemical formula: C_{7}H_{9}N \\ \hline \hline 95-80-7 & 2,4-toluylenediamine; 4-methyl-m-phenylenediamine \\ Chemical formula: C_{7}H_{10}N_2 \\ \hline \hline 137-17-7 & 2,4,5-trimethylaniline \\ Chemical formula: C_{9}H_{13}N \\ \hline \hline 90-04-0 & o-anisidine \\ Chemical formula: C_{7}H_{9}NO \\ \hline \hline 60-09-3 & 4-aminoazobenzene \\ \hline \end{array} $		
120-71-8	838-88-0	
Chemical formula: C ₈ H ₁₁ NO 101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 0-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	100 71 0	
101-14-4 4,4'-methylene-bis-(2-chloroanilene) Chemical formula: C ₁₃ H ₁₂ C ₁₂ N 101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 0-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	120-71-8	
$\begin{array}{c} \text{Chemical formula: $C_{13}H_{12}C_{12}N$} \\ 101-80-4 & 4,4'\text{-oxideaniline} \\ \text{Chemical formula: $C_{12}H_{12}N_2O$} \\ 139-65-1 & 4,4'\text{-thiodianiline; $4,4'\text{-diaminodiphenylsulfide}$ \\ \text{Chemical formula: $C_{12}H_{12}N_2S$} \\ 95-53-4 & \text{o-toluidine} \\ \text{Chemical formula: C_7H_9N} \\ 95-80-7 & 2,4\text{-toluylenediamine; $4\text{-methyl-m-phenylenediamine}}$ \\ \text{Chemical formula: $C_7H_10N_2$} \\ 137-17-7 & 2,4,5\text{-trimethylaniline} \\ \text{Chemical formula: $C_9H_{13}N$} \\ 90-04-0 & \text{o-anisidine} \\ \text{Chemical formula: C_7H_9NO} \\ 60-09-3 & 4\text{-aminoazobenzene} \\ \end{array}$	101 11 1	
101-80-4 4,4'-oxideaniline Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	101-14-4	
Chemical formula: C ₁₂ H ₁₂ N ₂ O 139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	101 00 4	
139-65-1 4,4'-thiodianiline; 4,4'-diaminodiphenylsulfide Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 O-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 O-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	101-60-4	,
Chemical formula: C ₁₂ H ₁₂ N ₂ S 95-53-4 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	130.65.1	
95-53-4 o-toluidine Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	139-03-1	
Chemical formula: C ₇ H ₉ N 95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	95-53-4	
95-80-7 2,4-toluylenediamine; 4-methyl-m-phenylenediamine Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	33-33-4	
Chemical formula: C ₇ H ₁₀ N ₂ 137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	95-80-7	
137-17-7 2,4,5-trimethylaniline Chemical formula: C ₉ H ₁₃ N 90-04-0 0-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	00001	
Chemical formula: C ₉ H ₁₃ N 90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	137-17-7	
90-04-0 o-anisidine Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	'0' ''	
Chemical formula: C ₇ H ₉ NO 60-09-3 4-aminoazobenzene	90-04-0	
60-09-3 4-aminoazobenzene		
	60-09-3	
		Chemical formula: C ₁₂ H ₁₁ N ₃



19) Formaldehyde

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	The wooden products made from fiberboard, particleboard, or plywood, which are employed in products.	- The details are as follows.	Banned
Threshold level	- Obtain the value by any one of the following 1) With a chamber method(EN 717-1:2004) Concentration in the air: Equal to or less that volume is 12 m³, 1 m³, or 0.0225 m³ 2) With a perforator method(EN 120:1992) - Equal to or less than 6.5 mg in 100 g of a during six months) - Equal to or less than 7.0 mg in 100 g of a during six months) - Equal to or less than 8.0 mg in 100 g of a derived from the one-time measurement 3) With a desiccator method(JIS A 5905 Fiberbo	n 0.1 ppm (or 0.124 mg/m³) in ar a particleboard without a surface a fiberboard without a surface trea a particleboard/fiberboard without based on EN120)	treatment (the average value atment (the average value a surface treatment (the value
	Average content: 0.5 mg/ℓ or lessMaximum content: 0.7 mg/ℓ or less (Use	N=2 to check the average and m	aximum values.)

20) Specific benzotriazole (*20)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (ultraviolet absorbers, etc.)	- Intentionally added	Banned
*20 Note - The target substance is 2-(3',5'-Di-tert-butyl-2'-hydroxyphenyl)benzotriazole (CAS No.3846-71-7).			

21) Dimethyl fumarate (DMF) (*21)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	All uses (moisture indicator used for a desiccant agent (e.g. silica gel), etc)	- More than 0.1 ppm of the materials	Banned
*21 Note - The target substance is CAS No. 624-49-7 and Chemical formula C ₆ H ₈ O ₄ . - Other usage: Materials such as adhesive, molding materials, ink, varnish, a wire rod, ferrite core, the capacitor.			rire rod, ferrite core, the

22) Beryllium oxide (*22)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (heat sinks, etc.)	- Intentionally added	Banned
*22 Note - Oxide of beryllium expressed in chemical formula BeO.			

23) Beryllium copper (*23)

Targets		Targets	Criteria/threshold levels	Effective date of the ban on the delivery	
Level 3	-	All uses (Springs, etc.)	- Intentionally added	N/A	
Exception	ception - Use as the material for laminating the magnetic head (because a replacement does not exist)				
*23 Note					

24) Cobalt dichloride

Targets			Criteria/threshold levels	Effective date of the ban on the delivery	
Level 1	-	Moisture indicator used for a desiccant agent (e.g. silica gel) Humidity indicator card which is impregnated with cobalt dichloride	-	Intentionally added	Banned



25) Diarsenic trioxide, Diarsenic pentaoxide (*25)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	Antifoam agents or fining agents for LCD panels (including cover glasses, touchscreens, and backlights)	- More than 1000 ppm (or 0.1 wt%) of the parts	Banned
*25 Note	 The target substances are following two maters of the common of the commo	oxide (CAS No.1327-53-3) of arse	

26) Bis (2-ethylhexyl) phthalate, Dibutyl phthalate, Benzyl butyl phthalate, Diisobutyl phthalate (*26)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	 Parts and materials for non-electrical and electronic equipment (e.g. carrying bags, carrying cases, carrying pouches, plastic bag, shrink film) Parts and materials that are in a constant contact with human body e.g. grip, handle 	- More than 1000 ppm (or 0.1 wt%) of the materials	Banned
Level 2	 Parts and materials for electrical and electronic equipment All packaging components and materials All applications other than the above 	- More than 1000 ppm (or 0.1 wt%) of the materials	N/A
*26 Note	The target substances are following 4 materi Bis(2-ethylhexyl) phthalate, Di (2-ethylhexyl) Dibutyl phthalate, Di-n-butyl phthalate Benzyl butyl phthalate, Butyl benzyl phthalate Diisobutyl phthalate, Di-i-butyl phthalate A threshold level is applied every material.	xyl) phthalate (CAS No. 117-8 ⁻ (CAS No. 84-74-	1-7) 2) -7)



27) Di-isononyl phthalate, Di-isodecyl phthalate, Di-n-octyl phthalate, Di-n-hexyl phthalate, "1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich",

"1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters", Bis(2-methoxyethyl) phthalate, Diisopentylphthalate, "1,2-Benzenedicarboxylic acid, dipentylester, branched and linear", N-pentyl-isopentylphthalate, Dipentyl phthalate (*27)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery		
Level 3	- All uses (plasticizer of plastics)	- More than 1000 ppm (or	N/A		
		0.1 wt%) of the parts			
*27 Note	- The target substances are following 11 mater	rials. For details, refer to table 4	1.2.2.		
	- Di-isononyl phthalate (CAS No. 28553-12	2-0, 68515-48-0)			
	- Di-isodecyl phthalate (CAS No. 26761-40	0-0, 68515-49-1)			
	- Di-n-octyl phthalate (CAS No. 117-84-0)	,			
	- Di-n-hexyl phthalate (CAS No. 84-75-3)				
	- 1,2-Benzenedicarboxylic acid, di-C6-8-br	anched alkyl esters, C7-rich (CA	S No. 71888-89-6)		
	- 1,2-Benzenedicarboxylic acid, di-C7-11-b				
	_				
	, , , , , , , , , , , , , , , , , , , ,	52 57			
	, ,,	ster branched and linear"			
	, , ,				
 Bis(2-methoxyethyl) phthalate (CAS No. 117-82-8) Diisopentylphthalate "1,2-Benzenedicarboxylic acid, dipentylester, branched and linear" N-pentyl-isopentylphthalate Dipentyl phthalate A threshold levels are applied every material. 					



Table 4.2.2 List of specific phthalates (phthalic esters)

Abbreviation	CAS No.	Name / Chemical formula / Use
DEHP	117-81-7	Bis (2-ethylhexyl)phthalate; Di (2-ethylhexyl) phthalate
		Chemical formula: C ₂₄ H ₃₈ O ₄
		Usage examples: Plasticizer of the emulsion system adhesive, diluent of the epoxy
		resin-based adhesive
DBP	84-74-2	Dibutyl phthalate; Di-n-butyl phthalate
		Chemical formula: C ₁₆ H ₂₂ O ₄
		Usage examples: Plasticizer of the emulsion system adhesive, diluent of the epoxy
		resin-based adhesive
BBP	85-68-7	Benzyl butyl phthalate; Butyl benzyl phthalate
		Chemical formula: C ₁₉ H ₂₀ O ₄
		Usage examples: Plasticizer
DIBP	84-69-5	Diisobutyl phthalate; Di-i-butyl phthalate
וטוטו	01000	Chemical formula: C ₁₆ H ₂₂ O ₄
		Usage examples: Plasticizer
DINP	28553-12-0	Di-isononyl phthalate; Diisononyl phthalate
DIN	68515-48-0	Chemical formula: C ₂₆ H ₄₂ O ₄
	00313-40-0	Usage examples: General-purpose plasticizer, electric wire coating, wall paper
DIDP	26761-40-0	Di-isodecyl phthalate; Diisodecyl phthalate
סוטר		
	68515-49-1	20 10 1
DNOD	447.04.0	Usage examples: Insulating improved additive, electric wire coating
DNOP	117-84-0	Di-n-octyl phthalate
		Chemical formula: C ₂₄ H ₃₈ O ₄
DAILID	04.75.0	Usage examples: General-purpose plasticizer, electric wire coating, film, blood bag
DNHP	84-75-3	Di-n-hexyl phthalate
		Chemical formula: C ₂₀ H ₃₀ O ₄
		Usage examples: Plasticizer for polyvinyl chloride
DIHP	71888-89-6	1,2-Benzenedicarboxylic acid, di-C6-8-branched alkyl esters, C7-rich
		Chemical formula: C ₂₂ H ₃₄ O ₄
		Usage examples: Hardening agent of the epoxy resin-based adhesive
DHNUP	68515-42-4	1,2-Benzenedicarboxylic acid, di-C7-11-branched and linear alkyl esters
		Chemical formula: C ₂₀ H ₃₀ O ₄
		Usage examples: Plasticizer for the insulators of telecommunications apparatus used at
		the time of plastics manufacturing.
DMEP	117-82-8	Bis(2-methoxyethyl) phthalate
		Chemical formula: C ₁₄ H ₁₈ O ₆
		Usage examples: The plasticizer which improves the durability of the polyurethane resin
DIPP	605-50-5	Diisopentylphthalate
		Chemical formula: C ₁₈ H ₂₆ O ₄
		Usage examples: Plasticizer
-	84777-06-0	1,2-Benzenedicarboxylic acid, dipentylester, branched and linear
		Chemical formula: C ₁₈ H ₂₆ O ₄
		Usage examples: Plasticizer
-	776297-69-9	N-pentyl-isopentylphthalate
		Chemical formula: C ₁₈ H ₂₆ O ₄
		Usage examples: Plasticizer
DPP	131-18-0	Dipentyl phthalate
		Chemical formula: C ₁₈ H ₂₆ O ₄
		Usage examples: Plasticizer
	1	1 - 2 - 3 - 3 - 3 - 3 - 3 - 3 - 3 - 3 - 3



28) Hydrofluorocarbon (HFC), Perfluorocarbon (PFC), Sulfur hexafluoride (SF₆)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- Uses installed into product (e.g. refrigerant and insulation)	- Intentionally added	Banned

29) Ozone depleting substances (ODS) (*29)

	Targ	ets	Criteria/threshold levels	Effective date of the ban on the delivery		
Level 1	- Uses installed	ed into product (e.g. refrigerant on)	- Intentionally added	Banned		
	- All uses (cle	aning agents, etc.)	Treatments such as cleaning and foaming			
*29 Note	List of ozone de	pleting substances (ODS)				
	CAS No.	Name				
	75-69-4	CFC-11; trichlorofluorometha	ane			
	75-71-8	CFC-12; dichlorofluorometha	ane			
	76-13-1	CFC-113; trichlorofluoroetha	CFC-113; trichlorofluoroethane			
	76-14-2	CFC-114; dichlorotetrafluoroethane				
	76-15-3	CFC-115; chloropentafluoroethane				
	353-59-3	Halon-1211; bromochlorodifluoromethan				
	75-63-8	Halon-1301; bromotrifluoromethane				
	124-73-2	Halon-2402; dibromotetrafluoroethane				
	76-72-9	CFC-13; chlorotrifluoromethane				
	354-56-3	CFC-111; pentachlorofluoroethane				
	76-12-0	CFC-112; tetrachlorodifluoroethane				
	422-78-6	CFC-211; heptachlorofluoropropane				
	3182-26-1	CFC-212; hexachlorodifluoropropane				
	2354-06-5	CFC-213; pentachlorotrifluoropropane				
	29255-31-0	CFC-214; tetrachlorotetraflu	CFC-214; tetrachlorotetrafluoropropane			
	4259-43-2	CFC-215; trichloropentafluoropropane				
	661-97-2	CFC-216; dichlorohexafluoro	CFC-216; dichlorohexafluoropropane			
	422-86-6	CFC-217; chloroheptafluorop				
	56-23-58	Carbon tetrachloride; tetrach	loromethane			
	71-55-6	1,1,1-Trichloroethane; methy	/l chloroform			

30) Perfluorooctane sulfonates (PFOS)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses (water repellant agents, etc)	- Intentionally added	Banned
Exception	- Resists for semiconductors		

31) Boric acid, specific sodium borates (*31)

	Tar	gets	Criteria/threshold levels	Effective date of the ban on the delivery			
Level 3	- All uses (flame retardants, etc.)		- More than 1000 ppm (or 0.1 wt%) of the parts	N/A			
*31 Note	List of boric acid	ds and specified sodium borates					
	CAS No.	Name and other information	Name and other information				
	10043-35-3	Boric acid					
		Chemical formula: BH₃O₃					
		Use: Borate glass, fiberglass, l	oron-based compound metal				
	11113-50-1	Boric acid					
		Chemical formula: BH₃O₃					
	12179-04-3	Disodium tetraborate, anhydrous; Tetraboron disodium heptaoxide pentahydrate					
	1330-43-4	Disodium tetraborate, anhydrous; Tetraboron disodium heptaoxide					
	1303-96-4	Disodium tetraborate, anhydro	Disodium tetraborate, anhydrous; Disodium tetraborate decahydrate; Borax				
	12267-73-1	Tetraboron disodium heptaoxic	Tetraboron disodium heptaoxide, hydrate				



32) 4-(1,1,3,3-tetramethylbutyl) phenol (*32)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	- All uses (surfactant, etc.)	- More than 1000 ppm (or	N/A
		0.1 wt%) of the parts	
*32 Note	- The target substance is following material.		
	CAS No. 140-66-9		
	Chemical formula: C ₁₄ H ₂₂ O		
	Synonym: 4-tert-Octylphenol		

33) Bis(2-methoxyethyl) ether (*33)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	- All uses (solvent for dissolving electrolyte	- More than 1000 ppm (or	N/A
	of battery, etc.)	0.1 wt%) of the parts	
*33 Note	- The target substance is following material. CAS No. 111-96-6		
	Chemical formula: C ₆ H ₁₄ O ₃ Synonym: Diethylene glycol dimethyl ether;	Diglyme	

34) N,N-dimethylacetamide (DMAc) (*34)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery	
Level 3	- All uses (cleaning agents, etc.)	- More than 1000 ppm (or	N/A	
		0.1 wt%) of the parts		
*34 Note	- The target substance is following material.			
	CAS No. 127-19-5			
	Chemical formula: C₄H ₉ NO			
	Synonym: DMA、DMAC			
	- Use: As a polar solvent of the high boiling point, it is used in organic synthetic chemistry widely.			

35) Ethylene glycol dimethyl ether (EGDME) (*35)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	All uses (solvent for dissolving electrolyte of lithium battery, etc.)	- More than 1000 ppm (or 0.1 wt%) of the parts	N/A
*35 Note	- The target substance is following material. CAS No. 110-71-4 Synonym: 1,2-dimethoxyethane		

36) Perchlorates

,			
Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	- All uses (oxidizers for matches, etc.)	- 6 ppb (or 0.006 ppm) or more of the parts	N/A

37) Perfluorooctanoic acid (PFOA) and individual salts and esters of PFOA (*37)

		Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1		Coatings applied to textiles, leathers and fabrics	-	More than 1 μg/m² of the coated material	Banned
	-	All applications other than above and Level 2	-	More than 1000 ppm (or 0.1 wt%) of the parts	Banned
		Photographic coatings applied to films, papers, or printing plates	-	More than 1 μg/m² of the coated material	Banned
		Additives for adhesives, foil or tape in semiconductor	ı	More than 1000 ppm (or 0.1 wt%) of the parts	Banned
*37 Note	-	CAS No. 335-67-1, 3825-26-1, 335-95-5, 2395-00-8, 335-93-3, 335-66-0, 376-27-2, 3108-24-5			



38) Polycyclic aromatic hydrocarbons (PAH) (*38)

	Targets	Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	Rubber or plastic components that come into direct as well as prolonged or short-term repetitive contact with the human skin or the oral cavity, under normal or reasonably foreseeable conditions of use	- More than 1 ppm (or 0.0001 wt%) of the material	Banned
*38 Note	- CAS No. 50-32-8, 192-97-2, 56-55-3, 218-01	-9, 205-99-2, 205-82-3, 207-08-9	9, 53-70-3

39) Trixylyl phosphate (TXP) (*39)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 3	- All uses (additives for resins, etc.)	- More than 1000 ppm (or 0.1 wt%) of the parts	N/A
*39 Note	- CAS No. 25155-23-1		

40) Radioactive materials (*40)

Targets		Criteria/threshold levels	Effective date of the ban on the delivery
Level 1	- All uses	- Intentionally added	Banned
*40 Note	- The example of the target substances CAS No. 7440-46-2, Cesium (Cs)		



5 Additional rules for packaging components and materials

5.1 Definition of "packaging components and materials"

Packaging components and materials are defined as products made from any materials and components of any nature to be used for the containment, protection, handling, delivery and presentation of goods, from raw materials to processed goods from the manufacturer to the customer.

However, the definition excludes the components and materials for the returnable boxes, which are reused or recycled under the control of carriers or parts suppliers, and are not disposed of by end-users or Magnescale Co., Ltd.



5.2 Additional rules for packaging components and materials

Heavy metals (cadmium, lead, mercury, and hexavalent chromium)

Torque (Critaria/threshold levels (*A)	Effective date of the	
Targets		Criteria/threshold levels (*A)	ban on the delivery	
Level 1	All packaging components and materials Some examples are given in PACKAGING of Table 5.2.1	100 ppm(or 0.1 wt%) or more of the total-concentration of four heavy metals (cadmium, lead, mercury, and hexavalent chromium) contained in each part, ink, or paint that constitutes a package.	Banned	
Exception	- Cartons for returnable boxes owned by carr	iers or parts suppliers		
*A Note	For hexavalent chromium: First analyze total chromium content and and total chromium is less than 100 ppm When analyzing, the same sample preparapplicable. If this total concentration is more than 10 concentration is less than the 100 ppm li When the sum of the cadmium, lead and and confirm that no hexavalent chromium hexavalent chromium provided in this cla	n. aration methods as those used for 00 ppm, verify that the sum of the imit. I mercury concentration is less the in is present, using the standard in	or cadmium and lead are cadmium, lead and mercury and the 100 ppm limit, analyze	
	 Standard methods for detecting hexavalent chromium: Note: Standard methods specified hereafter are applicable when total concentration of the four elements of cadmium, lead, mercury, and total chromium in packaging components and materials is 100 ppm or more Detection methods: Sample preparation Extraction methods such as boiling water extraction and alkaline extraction (e.g. IEC 62321:2008 Anne C, EPA 3060A) Measurement method Ultraviolet-Visible (UV/VIS) Spectroscopy (e.g. IEC 62321:2008 Annex C, EPA 7196A) If a combination of a sample preparation method and a measurement method can ensure the following limits of quantification, the combination is also available. Less than 5 ppm for mercury Less than 5 ppm for cadmium 			
	- Less than 5 ppm for the total chromium			
Standards for measurement	- Less than 30 ppm for lead 1) Sample preparation - For cadmium and lead, follow the methods - For total chromium, follow the methods secifies 2) Measurement methods Regarding the measurement of cadmium, leading the methods specified in Clause 4.2 Regarding the measurement of mercury cowhen the mercury concentration is predicted methods: - A reduction-evaporation atom-absorption	ead, and total-chromium concent 1), 2). ncentrations, follow the method sed to be low, you are advised to u	rations, specified in Clause 4.2 3).	
	ICP-OES (ICP-AES) method with a hydr ICP-MS method with a hydride-generation	ide-generation apparatus		



Table 5.2.1 Illustrative examples of packing components/materials

Note: These does not cover all packing parts, materials here.

No	Name	Description
1.	Carton	Including master carton and sub-master carton made from any materials.
2.	Cusion	
3.	Protection bag,	Such as made from foamed plastic or nonwoven fabric
	protection sheet	
4.	Plastic bag	
5.	Gas barrier envelop	
6.	Envelop	Such as used for warranty card
7.	Film	Including protection films such as used for the LCD displays
8.	Separator, spacer,	
	partition	
9.	Printing ink	Used for packaging components
10.	Adhesive tape	Such as used for closing carton or poly bag, or, fixing or protection for removable component
11.	Label	Attached to the packaging components under control of Magnescale Co., Ltd., such as
		bar-code label
12.	Crate	Such as wooden frame
13.	Shrink film	
14.	Jewel box	Such as packaging for accesory for the Gauging probe
15.	Magazine stick	Such as used for IC
16.	Stopper	
17.	Tray	Such as used for IC
18.	Reel	Such as used for resistors and/or capacitors
19.	Pallet	Made from wood, plastic, paper, etc. which is used in one-way
		transportation, including slip sheet.
20.	Wooden box	
21.	Stretch film	Wrap around palletized unit
22.	Wooden container	
23.	Items used for over	Such as carton, cushion, adhesive tape, etc. which is used for component delivery
	packaging	
24.	Band, string	Such as PP band

6 Revisions

Edition	Released date	Remarks
1	18 January, 2010	Japanese edition 1
2	15 March, 2010	Japanese edition 2
3	1 August, 2010	Janapese / English edition 3
4	1 June, 2012	Janapese / English edition 4
5	13 January, 2014	English edition 5
6	27 February, 2015	English edition 6
7	24 March, 2015	English edition 7
8	12 September, 2017	English edition 8
9	28 February, 2018	English edition 9 < Latest edition >